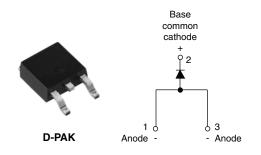




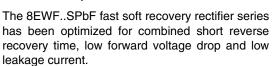
Vishay High Power Products

Surface Mountable Fast Soft Recovery Diode, 8 A



PRODUCT SUMMARY				
V _F at 8 A < 1.2 V				
t _{rr} 55 ns				
V _{RRM}	200 to 600 V			

FEATURES/DESCRIPTION





The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

This series is designed and qualified for industrial level.

Compliant to RoHS directive 2002/95/EC.

APPLICATIONS

- Output rectification and freewheeling diode in inverters, choppers and converters
- Input rectifications where severe restrictions on conducted EMI should be met

MAJOR RATINGS AND CHARACTERISTICS						
SYMBOL CHARACTERISTICS VALUES UN						
I _{F(AV)}	Sinusoidal waveform	8	A			
V _{RRM}		200 to 600	V			
I _{FSM}		170	A			
V _F	8 A, T _J = 25 °C	1.2	V			
t _{rr}	1 A, 100 A/μs	55	ns			
TJ	Range	- 40 to 150	°C			

VOLTAGE RATINGS			
PART NUMBER	V _{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V _{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I _{RRM} AT 150 °C mA
8EWF02SPbF	200	300	
8EWF04SPbF	400	500	3
8EWF06SPbF	600	700	

ABSOLUTE MAXIMUM RATINGS						
PARAMETER SYMBOL TEST CONDITIONS				UNITS		
Maximum average forward current	I _{F(AV)}	T _C = 96 °C, 180° conduction half sine wave	8			
Maximum peak one cycle	I _{FSM}	10 ms sine pulse, rated V _{RRM} applied	170	А		
non-repetitive surge current		10 ms sine pulse, no voltage reapplied	200			
Maximum I ² t for fusing	l ² t	10 ms sine pulse, rated V _{RRM} applied	140	A ² s		
Maximum 1-t for fusing 1-t		10 ms sine pulse, no voltage reapplied	200	A-5		
Maximum I²√t for fusing	I²√t	t = 0.1 ms to 10 ms, no voltage reapplied	2000	A ² √s		

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ELECTRICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CO	TEST CONDITIONS			
Maximum forward voltage drop	V _{FM}	8 A, T _J = 25 °C	1.2	V		
Forward slope resistance	r _t	T _{.I} = 150 °C	16	mΩ		
Threshold voltage	V _{F(TO)}	1 1 = 150 C	1.13	V		
Maximum reverse leakage current		T _J = 25 °C	V _B = Rated V _{BBM}	0.1	mA	
iviaximum reverse leakage current	I _{RM}	T _J = 150 °C	VR = nated VRRM	3	IIIA	

RECOVERY CHARACTERISTICS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	· •	
Reverse recovery time	t _{rr}	I _F at 8 Apk	140	ns	I _{FM}	
Reverse recovery current	I _{rr}	25 A/μs	2.6	Α	$t_a \mid t_b$	
Reverse recovery charge	Q _{rr}	T _J = 25 °C	0.25	μC	di/Q _{rr}	
Snap factor	S		0.5			

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum junction and storage temperature range	T _J , T _{Stg}		- 40 to 150	°C	
Soldering temperature	T _S	For 10 seconds	240		
Maximum thermal resistance, junction to case	R _{thJC}	DC operation	2.5	°C/W	
Typical thermal resistance, junction to ambient (PCB mount)	R _{thJA} (1)		50	· C/VV	
A constraint and a succional			1	g	
Approximate weight			0.03	OZ.	
Marking device		Case style TO-252AA (D-PAK)	8EWF	- 06S	

Note

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 $^{^{(1)}}$ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μm) copper 40 °C/W For recommended footprint and soldering techniques refer to application note #AN-994

Surface Mountable Vishay High Power Products Fast Soft Recovery Diode, 8 A

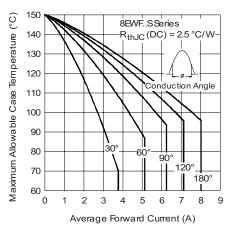


Fig. 1 - Current Rating Characteristics

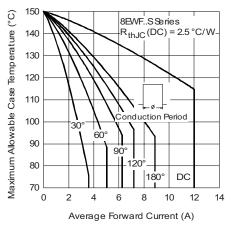


Fig. 2 - Current Rating Characteristics

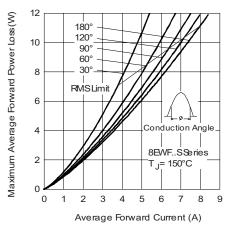


Fig. 3 - Forward Power Loss Characteristics

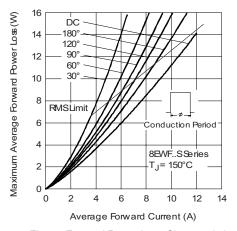


Fig. 4 - Forward Power Loss Characteristics

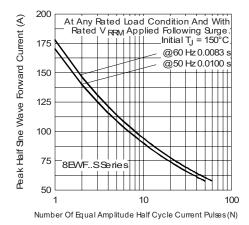


Fig. 5 - Maximum Non-Repetitive Surge Current

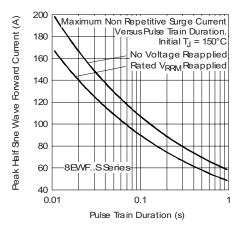


Fig. 6 - Maximum Non-Repetitive Surge Current

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Surface Mountable Fast Soft Recovery Diode, 8 A



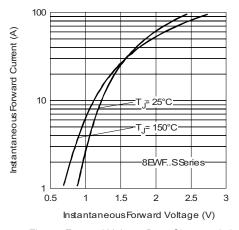


Fig. 7 - Forward Voltage Drop Characteristics

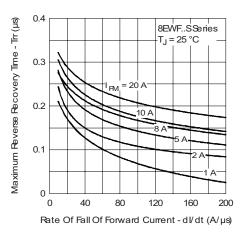


Fig. 8 - Recovery Time Characteristics, T_J = 25 °C

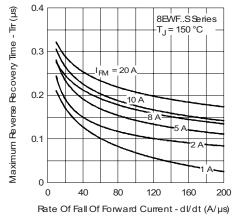


Fig. 9 - Recovery Time Characteristics, T_J = 150 °C

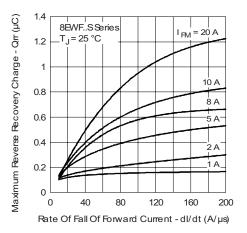


Fig. 10 - Recovery Charge Characteristics, $T_J = 25$ °C

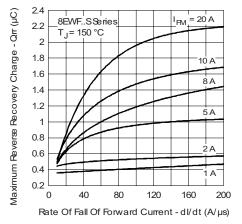


Fig. 11 - Recovery Charge Characteristics, T_J = 150 °C

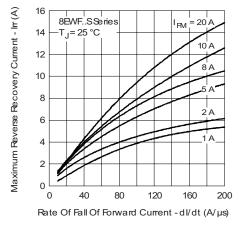


Fig. 12 - Recovery Current Characteristics, $T_J = 25$ °C



Surface Mountable Vishay High Power Products Fast Soft Recovery Diode, 8 A

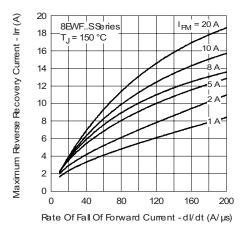


Fig. 13 - Recovery Current Characteristics, $T_J = 150 \, ^{\circ}\text{C}$

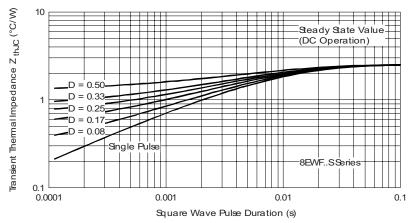


Fig. 14 - Thermal Impedance Z_{thJC} Characteristics

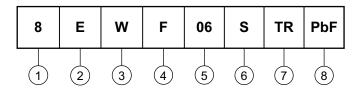
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Surface Mountable Fast Soft Recovery Diode, 8 A



ORDERING INFORMATION TABLE

Device code



- 1 Current rating (8 = 8 A)
- 2 Circuit configuration:

E = Single diode

3 - Package:

W = D-PAK

4 - Type of silicon:

F = Fast soft recovery rectifier $\sqrt{02 = 200 \text{ V}}$

Voltage code x 100 = V_{RRM} — 04 = 400 V

6 - S = Surface mountable

06 = 600 V

- 7 • TR = Tape and reel
 - TRR = Tape and reel (right oriented)
 - TRL = Tape and reel (left oriented)
- PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95016			
Part marking information	www.vishay.com/doc?95059			
Packaging information	www.vishay.com/doc?95033			

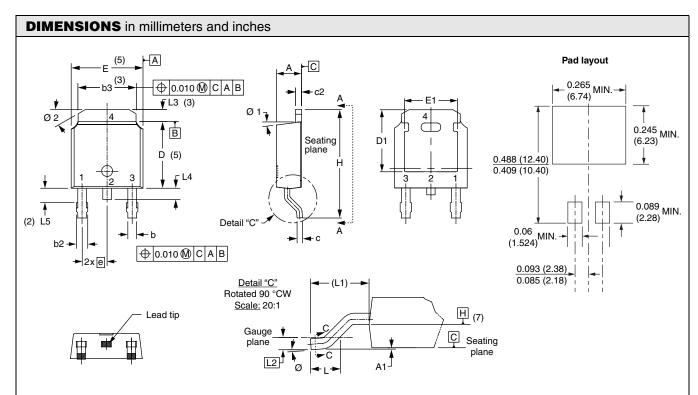
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Vishay High Power Products

D-PAK (TO-252AA)



SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
С	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	1	3
Е	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STWBOL	MIN.	MAX.	MIN.	MAX.	NOTES
е	2.29	BSC	0.090	0.090 BSC	
Н	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51	BSC	0.020	BSC	
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
Ø	0°	10°	0°	10°	
Ø1	0°	15°	0°	15°	
Ø2	25°	35°	25°	35°	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- $^{(7)}$ Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC outline TO-252AA





Vishay

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